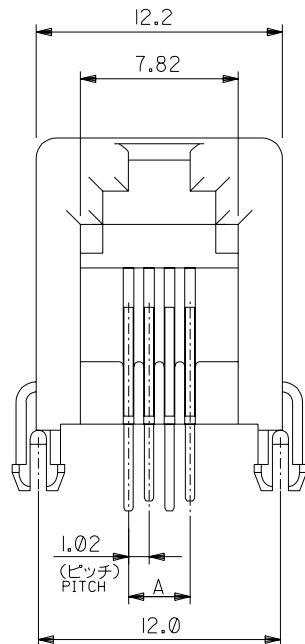
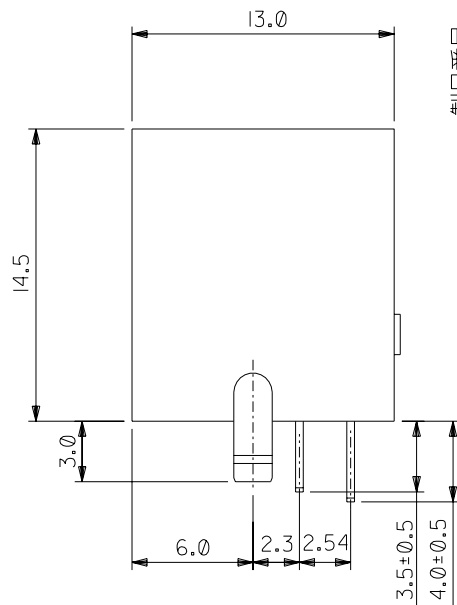
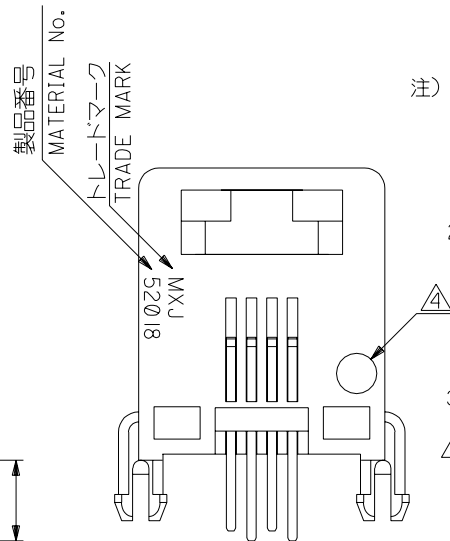
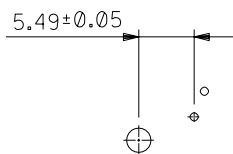




注) NOTES

1. 材質 MATERIAL
ハウジング：ガラス入りポリエステル UL94V-0
HSG. :POLYESTER G.F.15% UL94V-0
ターミナル：リン青銅
TERM.:PHOSPHOR BRONZE
2. メッキ仕様 PLATING
接点部 :金メッキ、表参照
CONTACT AREA: GOLD PER TABLE
半田付け部：錫メッキ 1.0μmMIN.
SOLDER AREA :TIN 1.0 MICROMETER MINIMUM.
下地メッキ：ニッケルメッキ 1.0μmMIN.
UNDERPLATE :NICKEL 1.0 MICROMETER MINIMUM.
3. 推奨基板厚：t=1.6±0.05
RECOMMENDED P.C.B. THICKNESS:1.6±0.05
4. 金メッキ厚標示
COLOR CODING TO INDICATE GOLD PLATING
黄色：0.1μmMIN.
YELLOW :0.1 MICROMETER MINIMUM.
緑色：0.38μmMIN.
GREEN :0.38 MICROMETER MINIMUM.
オレンジ色：0.76μmMIN.
ORANGE :0.76 MICROMETER MINIMUM.
無色：1.27μmMIN.
UNMARKED: 1.27 MICROMETER MINIMUM.
5. ハウジングの色は、グレイ。
HOUSING COLOR IS GRAY.
6. 本製品は52018-4**5の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 52018-4**5.



後番号 -42*6に適用

MATERIAL NO. SUFFIX -42*6

基板穴推奨寸法

RECOMMENDED P.C.B. LAYOUT
(ジャック取付け側)
(JACK ASS'Y SIDE)

後番号 -44*6に適用

MATERIAL NO. SUFFIX -44*6

4	4	3.05	1.27	52018-4446
			0.76	↑ -4436
			0.38	-4426
			0.1	↓ -4416
4	2	1.02	1.27	52018-4246
ポジション POSITION	極数 CIRCUITS	(A)	金メッキ厚 (μmMIN.) GOLD PLATING THK(MIN.) (μmMIN.)	製品番号 MATERIAL NO.
MODEL NO.		52018-4**6	DIMENSIONS:	
DESIGN UNITS		 THIRD ANGLE PROJECTION	☐ mm INCH	☐ INCH mm
☒ mm INCH	☒ mm ONLY		SHT REV OTHERWISE CAD ONLY	
DRAWN BY & DATE		TITLE: MODULAR JACK HOUSING ASS'Y -LEAD FREE-		
NAGATA '04/05/13				
CHECKED BY & DATE				
ITOJO '04/05/13		MOLEX INCORPORATED		
APPROVED BY & DATE				
SASAO '04/05/13				
DRAWING NO.		DRAWING NO.		SHEET NO.
D-52018-002.S01		SD-52018-002		I OF I
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.				
SIZE B				